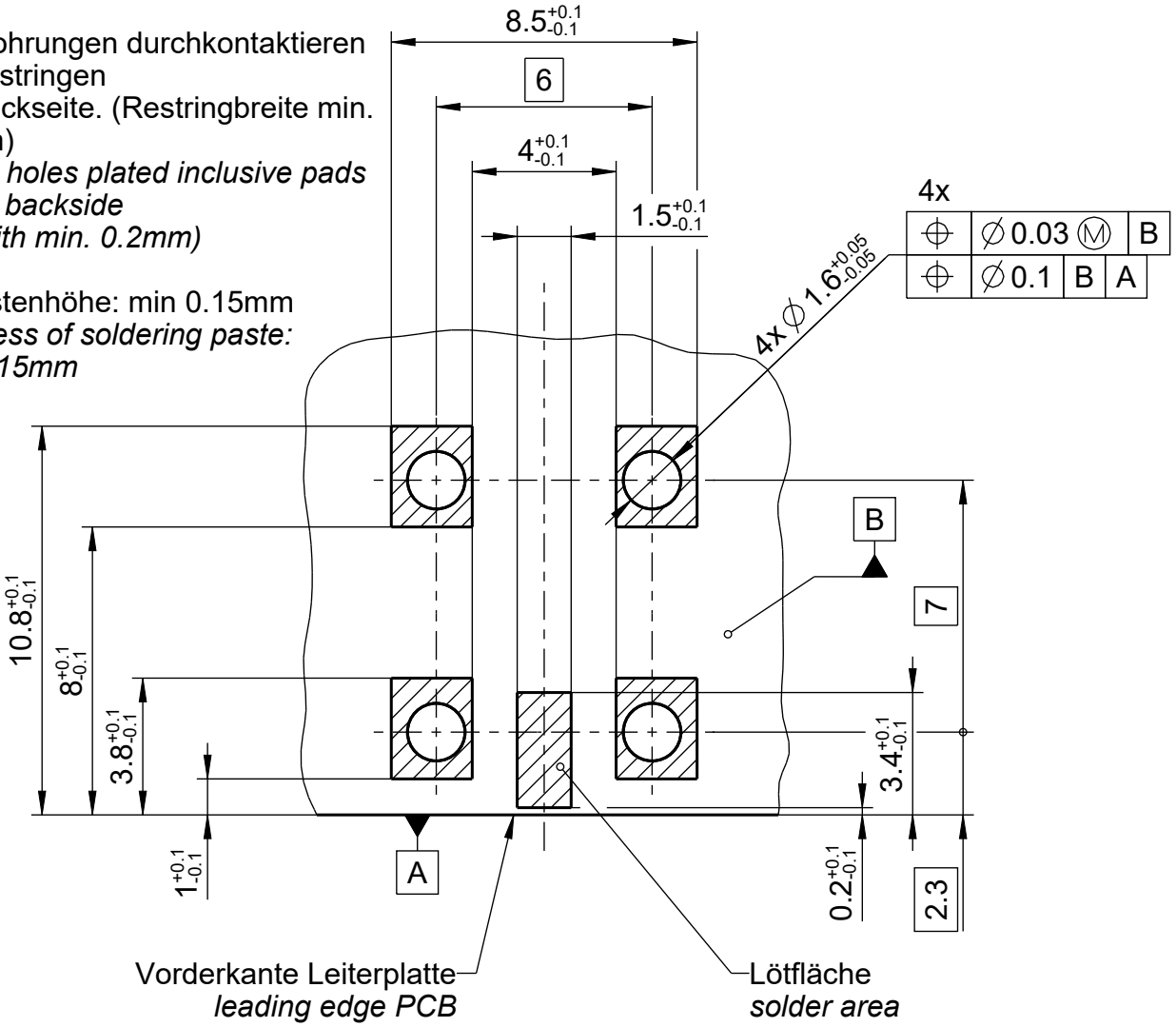
Leiterplatten-Layout
PCB layout
MB_581

Alle Bohrungen durchkontaktieren mit Restringen auf Rückseite. (Restringbreite min. 0.2mm)
all drill holes plated inclusive pads on the backside (padwith min. 0.2mm)

Lötpastenhöhe: min 0.15mm
thickness of soldering paste: min 0.15mm



Die angegebenen Maße und Toleranzen sind nur Empfehlungen.
The stated dimensions are only recommendations.

A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness and board-stackup are applied by customers. These parameteres have a strong impact on the high frequency performance of the mounted connector.
Please note, that the given layout ist not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommondation for optimuim solderability of the connector.
In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Rosenberger	*general tolerance* ISO 2768 mH	RN 006-01 dimensions <0,5 and symmetry	*scale:* 5:1 ( ) *weight[g]:* *surface[mm²]:*
			material:
vertraulich / *confidential*		*date* / *name*	*title:* Leiterplatten-Layout *PCB layout*
	drawn	29.03.2016 M_Bieberbach	
	check.	16.02.2018 M_Auer	
	appr.	19.02.2018 C5_Wagner	
	dimensioning incl. plating		
Size ISO 14405 Ⓔ Tolerancing ISO 8015			*drawing-no.:* MB_581 *sheet:* 1 *of:* 1
			remarks: .MB_355

rev.	*change-no*	*name*	*date*
a00	18-s093	M_Bieberbach	15.02.2018
100	16-v142	M_Bieberbach	25.10.2016

PD_FB_01
-METRIC-
ISO-Projektion Methode 1